Call for Papers
IEEE Aerospace and Electronic Systems Magazine

Special Issue on
Artificial Intelligence for Data Fusion

Throughout its several decades of history, the term artificial intelligence (AI) has described a wide field of different disciplines trying to mimic human intelligence in one way or the other. In view of rapidly increasing computational power and memory as well as huge data sets publicly available for training, testing and comparing algorithms, more and more application fields for AI arise. One field of that kind is given by data fusion. Its goal is to combine heterogeneous sensor and context data as well as other forms of information in order to get a concise and improved understanding of the underlying causes and phenomena, just as living creatures and in particular humans do.

This Special Issue will cover recent and ongoing developments of AI in the context of data fusion. In addition to survey articles discussing technical progress and current hot topics, historic aspects are to be discussed as well as legal and moral implications the use of AI may have.

Key Topic Areas in this context
- The history of AI
- Ongoing technical trends and the way ahead
- Non-technical aspects to be taken into account
- Human versus (or rather combined with) artificial intelligence
- New data fusion applications that benefit from AI

Submission and review of manuscripts are handled via the IEEE AESS Magazine's online system at https://sysaes.msubmit.net. Information on paper submission and the requisite contents for a full paper are available on that website, under Author Instructions. Manuscripts will be peer reviewed according to the standard IEEE AESS process.

We are looking forward for your valuable submission. In case you plan to submit, an e-mail to dietrich.fraenken@hensoldt.net stating that intention at your earliest convenience would be appreciated.

Important Dates
- Manuscript submission: February 29th, 2020
- Anticipated publication date: Winter 2020/21

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